%.%% /012304%506754%%

D	2017-5				
E	2021-1-27	4/7	e0.5-0.7 0.5-0.8 5 7		

2.0A

%%.%% 'D37@?>0% 9E2F?F%/9>2;<3G(9H I J%

%

Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V_{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V_{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50		40			A
Typical Junction Capacitance1）	C_j	220	80				pF
Typical Thermal Resistance2）	$R_{\theta JA}$	75					/W
Operating Junction Temperature Range	T_j	-55~+125					
Storage Temperature Range	T_{stg}	-55~+150					

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×(5×5mm^2）copper pad.

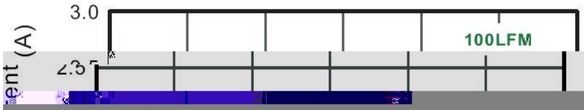
%

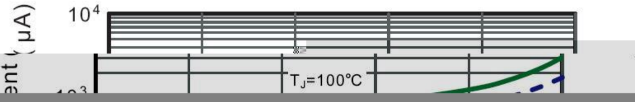
%%.%% +@06>5269@%BK9596>0523>263G(9H I J%

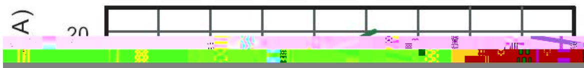
%

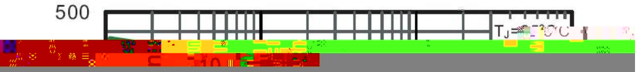
Parameter	Symbol	Test Conditions	数值 Rating					Unit
			MB24F	MB26F	MB28F	MB210F	MB220F	
Max Instantaneous Forward Voltage	V_F	I_F=2.0A	0.55	0.70	0.85			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25℃	0.5			0.3		mA
		T_a=100℃	10			5.0		mA

%%.%% +@06>5269@%BK9596>0523>26%B?510%



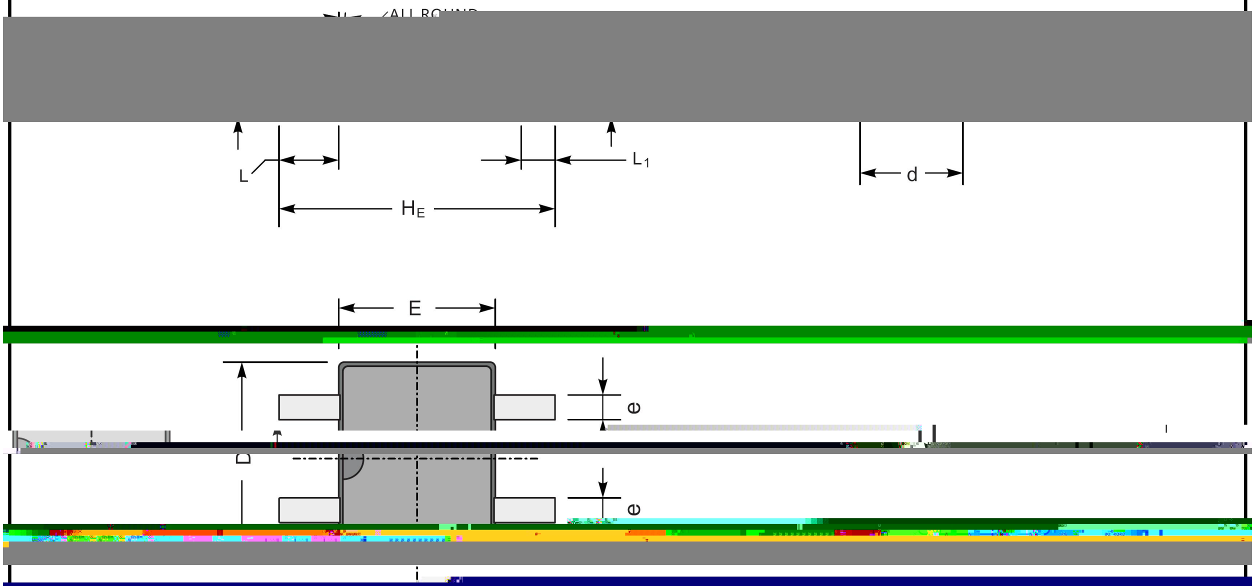




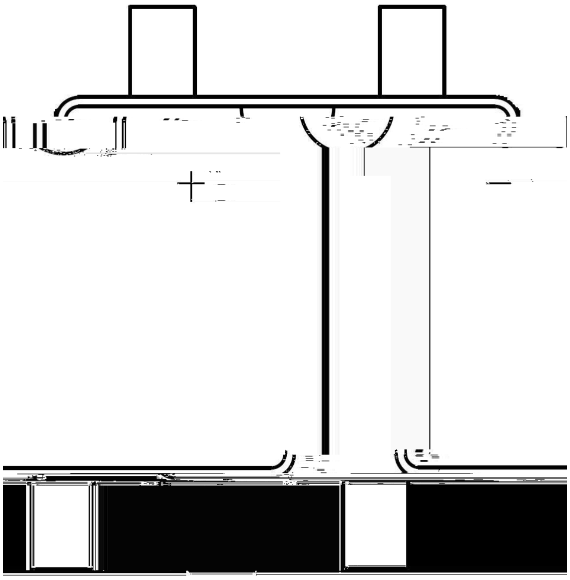


%%.%%C96:9<0%&2F0;327;3%

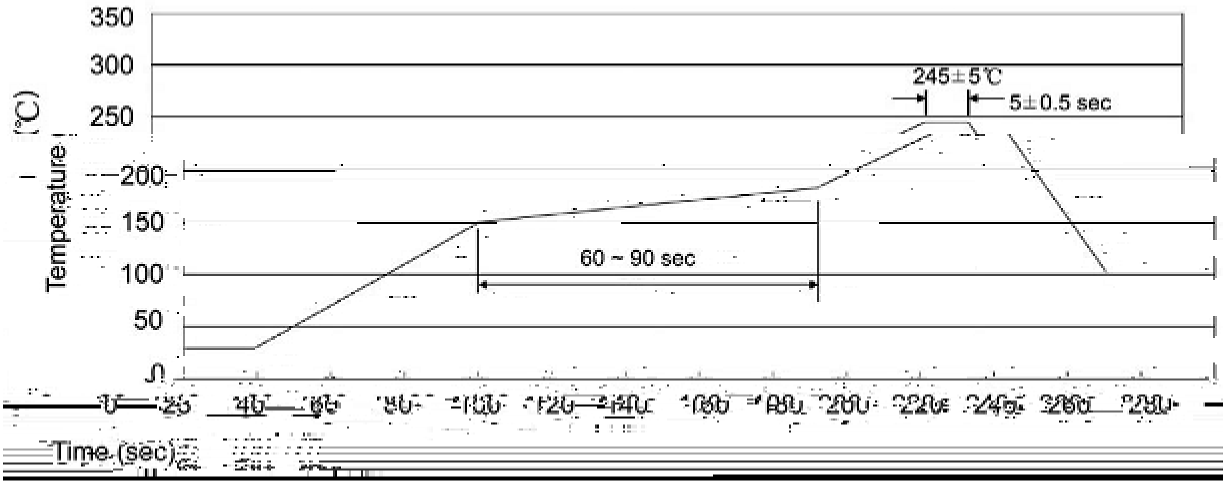
MBF



%%.%% 95:2;<%M;3>5?6>27;3%



G J%%.%%Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1 25 150 60 90sec;

2 245±5 5±0.5sec;

3 2 10 /sec.

1.Preheating:25~150 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

%%.%%% /0323>9;60%>7%)7@4052;<%*09>%(03>%B7;42>27;3%

260±5 10±1 sec.

Temp.:260±5 Time:10±1 sec

%%.%%C96:9<2;<%)C+BP%

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱